9 Scientific publications 2004

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10 Guests & special international relations

Guests from:

January 13	Prof. R. Bruch, University of Nevada, Reno
February & March	Prof. Zhuyi Wen, Chongqing University, China
February 19	Dr. Koichi Ohtaka, Takahito Uga, Ikuo Katoh, Ricoh Comp. Ltd., Japan
March 22	Mr. Natsuki Yokoyama, Hitachi Ltd., Tokyo, Japan
March 30	Valentin Kahl, ibidi GmbH, München
March 31	Mrs. Annie Roulleau, Fa. Sagem, St. Etienne , Frankreich
	Mr. Philiepe Pougnet, Johnson Controls, Cerey-Pontoise, Frankreich
May 8	Prof. R. Bruch, University of Nevada, Reno, USA
May 10	Prof. J.Morris, Portland State University, Portland, USA